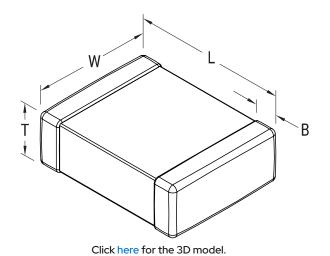


CBR02C299B3GAC

General Information

CBR-SMD RF COG, Ceramic, 2.9 pF, +/-0.1 pF, 25 VDC, COG, SMD, Fixed, RF, Ultra High Q, Low ESR, Class I, 0201



CBR-SMD RF COG Series Style SMD Chip Description SMD, Fixed, RF, Ultra High Q, Low ESR, Class I Features Ultra High Q, Low ESR, Class I RoHS Yes Termination Tin Marking No AEC-Q200 No Typical Component Weight 0.3 mg Notes Solder Reflow Only. Shelf Life 78 Weeks MSL 1

Dimensions	
Chip Size	0201
L	0.6mm +/-0.03mm
W	0.3mm +/-0.03mm
т	0.3mm +/-0.03mm
В	0.15mm +/-0.05mm

	0.3mm +/-0.03mm	Dielectric Withsta
	0.15mm +/-0.05mm	Temperature Ran
		Temp. Coefficien
tions		Dissipation Facto
	T&R, 180mm, Plastic Tape	Aging Rate
	15000	Insulation Resista

Specifications	
Capacitance	2.9 pF
Tolerance	+/-0.1 pF
Voltage DC	25 VDC
Dielectric Withstanding Voltage	62.5 VDC
Temperature Range	-55/+125°C
Temp. Coefficient	COG
Dissipation Factor	0.218%
Aging Rate	0% Loss/Decade Hour
Insulation Resistance	10 GOhms
Quality Factor	458

Statements of suitability for certain applications are based on our knowledge of typical operating conditions for such applications, but are not intended to constitute - and we specifically disclaim - any warranty concerning suitability for a specific customer application or use. This Information is intended for use only by customers who have the requisite experience and capability to determine the correct products for their application. Any technical advice inferred from this Information or otherwise provided by us with reference to the use of our products is given gratis, and we assume no obligation or liability for the advice given or results obtained.

Packaging Specifica

Packaging Quantity

Packaging